

MicroTech Annual Conference & Exhibition

“Power in Packaging”

CALL FOR ABSTRACTS

Register at: <https://www.imaps.org.uk/events/microtech-2019-power-in-packaging/>

IMAPS-UK Technical Conference



Granta Centre, Granta Park, Cambridge - 4th April 2019

MicroTech 2019 is the annual IMAPS-UK Conference & Exhibition which this year, focuses on the rapidly developing UK Power Electronics & Semiconductor Industry.

Electric & autonomous vehicles developments hint at a future that has the potential to revolutionise the way we live our lives. Demand for renewable energy generation and the pressures on power distribution will only grow to support the demands of this increasingly electrified world.

Microtech 2019 highlights many of the emerging technologies driven by this rapidly developing industry, touching on technologies & assembly processes common to all areas of the microelectronics community.

Advancements in power electronics and semiconductor packaging underpin many of these exciting changes. MicroTech 2019 will provide an opportunity to learn from leading industry experts and equipment manufactures as they share their experiences and developments in this rapidly changing industry.

Organizing Committee

Event Chair: Scott Wood Accelonix	Event Co-Chair: Matt Brown Inseto	General Co-Chair: Chris Powley Manufacturing Technology Centre
Technical Co-Chair: Carolyn Short SPTS Technologies Ltd	Technical Co-Chair: Brian Raeburn Disco Hi-Tech UK	Technical Co-Chair: John Lipp Science and Technology Facilities Council





Instructions for participation

We invite submission of abstracts in the following areas:

- **Research Papers:** These will describe high-impact academic research relating to the conference topics.
- **Technical Presentations:** Technical presentations showcasing in-production or pre-production techniques relating to the conference topics.
- **Current/Future trends:** Presentations demonstrating how markets related to the main conference topics are developing over time.

All abstracts received by the submission deadline will be evaluated by the technical committee. Abstracts covering a balanced range of the main conference topics will be selected and invited to provide an oral presentation (20mins + 5mins questions) or poster presentation (A0 size) during the conference. Some posters presenters may also be invited to provide a brief oral presentation showcasing their poster content to the full audience.

Conference topics

Power Electronics & Semiconductor Industry Trends	Packaging Technologies	Thermal Management & Materials	Design & Process Optimisation
<ul style="list-style-type: none"> • Compound Semiconductors • EV & Automotive • Power Storage • Power Distribution • Power Convertors • Smart Systems 	<ul style="list-style-type: none"> • Emerging Packaging Technologies • Assembly Processes • Embedded Technologies • System in Package 	<ul style="list-style-type: none"> • High Reliability • High Temperature Materials • Thermal Management • Material Handling 	<ul style="list-style-type: none"> • Process Modelling • System Integration • Power Density • Materials • Packaging Developments

Those wishing to present their work at MicroTech2018 should submit an abstract of approximately 200 words, electronically to: secretariat@imaps.org.uk

Deadlines

Abstract submission (200-300 words)	Fri 18 th Jan 2019
Confirmed speaker biographies and photographs	Fri 15 th Feb 2019
Final slide set or poster graphics (ppt or pdf)	Fri 15 th Mar 2019

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JOIN TODAY AND START SEEING THE BENEFITS!

telephone us 0131 202 9004

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visit us www.imaps.org.uk

